

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1-22. (Canceled)

23. (Currently Amended): A damping or soundproofing method for a substrate by forming at least two layers on at least one portion of the substrate,

wherein the at least two layers comprise:

a first cured product layer disposed on the substrate, wherein the first cured product layer is formed from a reactive fluid acrylic resin composition,

wherein the reactive fluid acrylic resin composition comprises

a composition including a resin selected from the group consisting of

(meth)acrylic ester resin, urethane (meth)acrylate resin and epoxy(meth)acrylate resin;

a photo-initiator; and

a (meth)acrylate monomer; and

a second cured product layer disposed on the first cured product layer, wherein the second cured product layer is formed from a reactive fluid epoxy resin composition.

24. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the at least two layers are formed by a process comprising:

forming the first cured product layer on the substrate; and

forming the second cured product layer on the first cured product layer.

25. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the at least two layers are formed by a process comprising:

applying the reactive fluid acrylic resin composition on the substrate to form a applied composition;

disposing the second cured product layer on the applied composition; and

curing the applied composition to form the first cured product layer.

26. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the first cured product layer is softer than the second cured product layer.

27. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the reactive fluid acrylic resin composition is a photo-curable acrylic resin composition.

***Claims 28 and 29 (Canceled).***

30. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the reactive fluid epoxy resin composition comprises:

a reactive resin having an epoxy group; and

a potent curing agent.

31. (Previously Presented): The damping or soundproofing method according to claim 30,

wherein the reactive fluid epoxy resin composition further comprises a filler.

32. (Previously Presented): The damping or soundproofing method according to claim 31,

wherein the filler comprises a metal powder.

33. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the second cured product layer has a hardness (JIS-D hardness) of 70 or more.

34. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the second cured product layer has a thickness of 10  $\mu\text{m}$  or more.

35. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the second cured product layer has a specific gravity of 1.4 or more.

36. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the first cured product layer has a hardness (JIS-A hardness) of 80 or less.

37. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the first cured product layer has a thickness of 10  $\mu\text{m}$  or more.

38. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein no part of the second cured product layer is directly formed on the substrate.

39. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the substrate has a concave part on its surface,

wherein the at least two layers are formed on the concave part.

40. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the at least two layers are formed on at least one surface of the substrate.

41. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the at least two layers comprise plurality of cured product layers different in glass transition temperature.

42. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the at least two layers are formed from fluid resin compositions each containing no tin compound.

43. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the at least two layers are formed from fluid resin compositions each containing no low molecular weight siloxane.

44. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the at least two layers comprise cured product layers each gives an outgas amount of 100 ppm or less.

45. (Previously Presented): The damping or soundproofing method according to claim 23,

wherein the substrate is a cover part for a HDD.